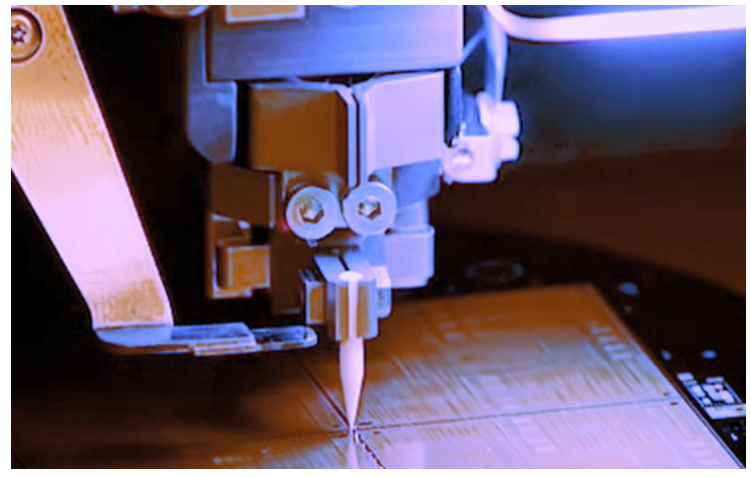
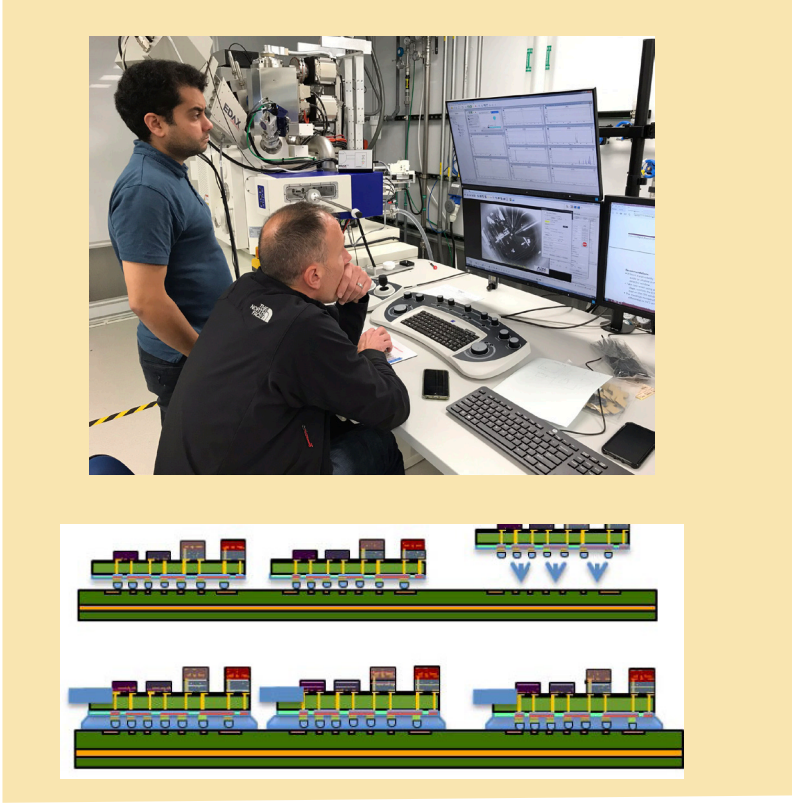


# Test Assembly and Packaging Facility (TAP)

The American Institute for Manufacturing Integrated Photonics TAP facility is the world's first open 300mm State-Of-The-Art advanced ecosystem for integrated silicon photonics test, assembly, and packaging. The TAP facility is a key component in AIM Photonics' end- to-end advanced manufacturing capability for photonic integrated circuits (PIC). The facility will have development and production process capability in key areas including wafer scale, chip scale and I/O attach. In addition the facility will have State-Of-The-Art Test and Metrology capability for each of these key functional areas.

### Benefits of AIM Photonics TAP Facility

- 300mm wafer compatibility
- Die attach for 2.5D and 3.0D packaging
- Automated fiber attach
- High speed automated Electro-optical testing
- Metrology for process capability evaluation
- MPW Compatibility
- Custom wafer compatibility



AIM Photonics, the world's leading Integrated Photonics Institute, has officially opened its 300mm Test, Assembly, and Packaging (TAP) facility. Organizations including; SMEs, universities, government labs, defense contractors, and fortune 500 companies have begun work in the world's first open 300mm PIC packaging and test facility.

AIM Photonics newly established manufacturing ecosystem has bridged the PIC development gap. AIM enables organizations of all sizes, to validate their next big PIC idea, and continues to set the standard for PIC technology design, fabrication, test, packaging, and final product implementation